

L Number	Hits	Search Text	DB	Time stamp
1	37150	double adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:01
2	46442	double adj layer\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:01
3	539533	capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:02
4	6604	(double adj layer\$5) near capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:02
5	98449	polarized	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:03
6	349	((double adj layer\$5) near capacitor) and polarized	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:03
7	213614	polariz\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:03
8	1621	((double adj layer\$5) near capacitor) and polariz\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:04
9	43	organic near solvent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:04
10	0	((((double adj layer\$5) near capacitor) and polariz\$5) and (organic near solvent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:05
11	299865	organic near solvent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:09
12	79	((((double adj layer\$5) near capacitor) and polarized) and (organic near solvent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:19

13	1049989	mold\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:20
14	17	((((double adj layer\$5) near capacitor) and polarized) and (organic near solvent)) and mold\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:21
15	3330	polariz\$5 near electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:22
16	1087	((double adj layer\$5) near capacitor) and (polariz\$5 near electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:22
17	15971	knead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:23
18	3	(organic near solvent) and (((double adj layer\$5) near capacitor) and (polariz\$5 near electrode)) and knead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:26
19	28479	polariz\$5 same electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:27
20	1087	(polariz\$5 near electrode) and ((double adj layer\$5) near capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:27
21	373	electrode near molding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:27
22	175	((polariz\$5 near electrode) and ((double adj layer\$5) near capacitor)) and mold\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:47
23	3	"20040179329"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:49
24	7	electrode adj molding adj process	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:50

25	56740	molding near process	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 16:51
26	12	((double adj layer\$5) near capacitor) and (molding near process)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:05
27	631	electrode near drying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:06
28	332637	expand	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:06
29	876667	expand\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:07
30	94	(electrode near drying) and expand\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:07
31	5	((electrode near drying) and expand\$5) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:08
32	169263	widen\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:08
33	5	(electrode near drying) and widen\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:18
34	3	continous near drying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:19
35	1554	continuous near drying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:19
36	4	vacumn near drying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:19

37	21121	vacuum near drying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:20
39	2	((double adj layer\$5) near capacitor) and ((continuous near drying) and (vacuum near drying))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:21
40	2	((continuous near drying) and (vacuum near drying)) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:21
38	67	(continuous near drying) and (vacuum near drying)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:46
41	49	"4862328"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:49
42	7	continous near dry\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:49
43	0	(continuous near drying) and "4862328"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:50
44	151400	drying and vacuum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:51
45	210	(drying and vacuum) and ((double adj layer\$5) near capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:55
46	84	((drying and vacuum) and ((double adj layer\$5) near capacitor)) and rolling	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 17:59
47	78	((((drying and vacuum) and ((double adj layer\$5) near capacitor)) and rolling) and sheet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:00
48	24	((((drying and vacuum) and ((double adj layer\$5) near capacitor)) and rolling) and sheet) and continuous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:08

49	1	rolling same drying same continuous same capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 18:09
----	---	--	---	------------------